SoundPower

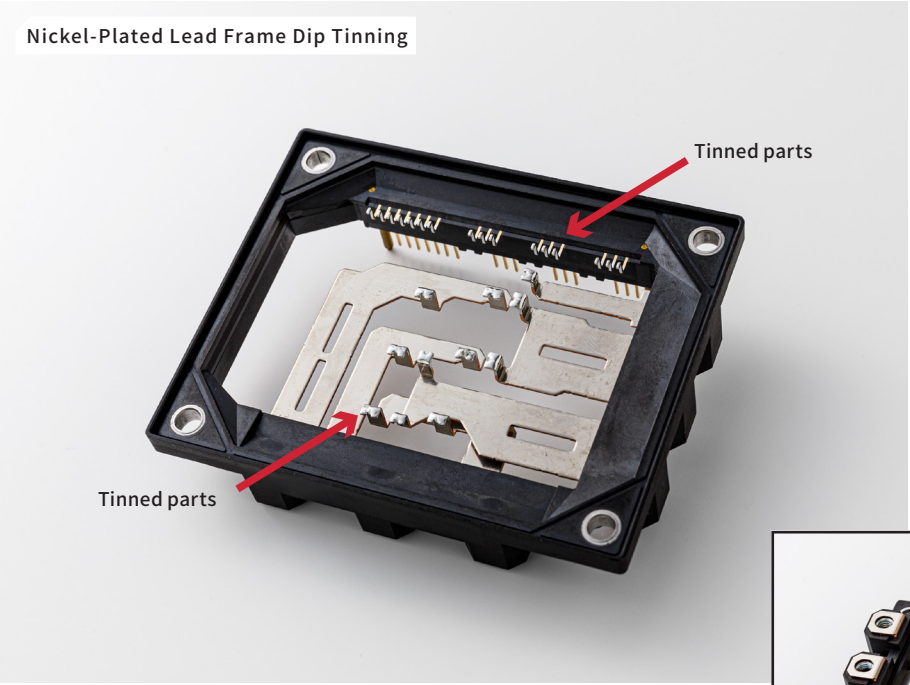
ULTEX

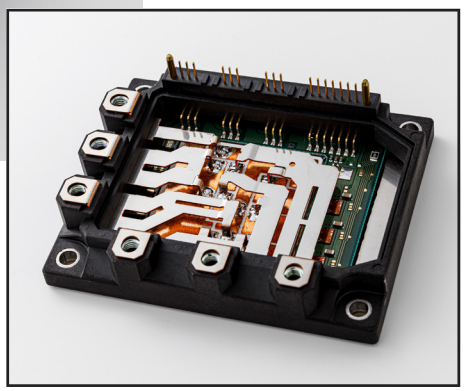
https://ultex.co.jp

Application

Soldering

Nickel-Plated Power Module Lead Tinning





Key Points

- Flux-free
- Solder diffusion bonding
- Silver-bearing lead-free solder
- No voids
- No dendrites

System Used

- CSS



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